Asynchronous Clear

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
′164	36 MHz	21 mW per bit
'LS164	36 MHz	10 mW per bit

description

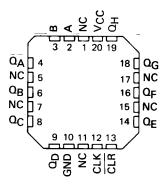
These 8-bit shift registers feature gated serial inputs and an asynchronous clear. The gated serial inputs (A and B) permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup-time requirements will be entered. Clocking occurs on the low-to-high-level transition of the clock input. All inputs are diode-clamped to minimize transmission-line effects.

The SN54164 and SN54LS164 are characterized for operation over the full military temperature range of $-55\,^{\circ}$ C to 125 $\,^{\circ}$ C. The SN74164 and SN74LS164 are characterized for operation from 0 $\,^{\circ}$ C to 70 $\,^{\circ}$ C.

SN54164, SN54LS164...J OR W PACKAGE SN74164...N PACKAGE SN74LS164...D OR N PACKAGE (TOP VIEW)

д [1 2	14 V _{CC}
$a_A \Box$	3	12 \(\oldsymbol{12} \)
α_{B} [4	11 QF
α _C □	5	10∏ Q E
$\sigma_{D} \sqsubset$	6	9 ☐ CLR
GND [7	8DCLK

SN54LS164 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE

L	INPUTS			OUTPUTS					
CLEAR	CLOCK	Α	В	α_{A}	α_{B}	Q _H			
L	X	Х	Х	L	L	L			
Н	L	×	Х	Q _{A0}	o_{B0}	α_{H0}			
Н	1	н	Н	Н	\mathbf{Q}_{An}	Q_{Gn}			
Н	1	L	X	L	\mathbf{Q}_{An}	q_{Gn}			
Н	1	Х	L	L	Q _{An}	Q_{Gn}			

H = high level (steady state), L = low level (steady state)

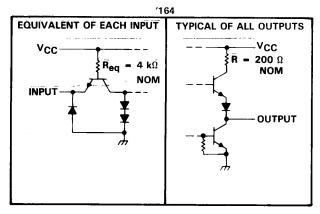
X = irrelevant (any input, including transitions)

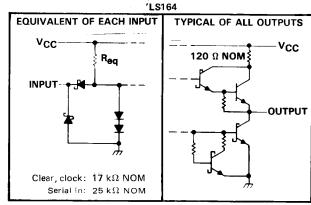
↑ = transition from low to high level.

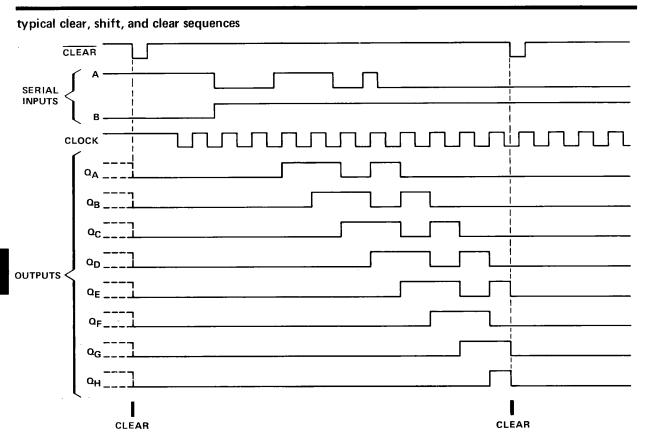
 ${
m Q}_{A0},\,{
m Q}_{B0},\,{
m Q}_{H0}$ = the level of ${
m Q}_A,\,{
m Q}_B,\,{
m or}\,\,{
m Q}_H,$ respectively, before the indicated steady-state input conditions were established.

Q_{An}, Q_{Gn} = the level of Q_A or Q_G before the most-recent ↑ transition of the clock; indicates a one-bit shift.

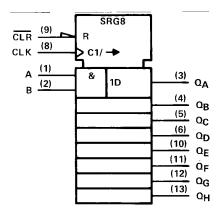
schematics of inputs and outputs





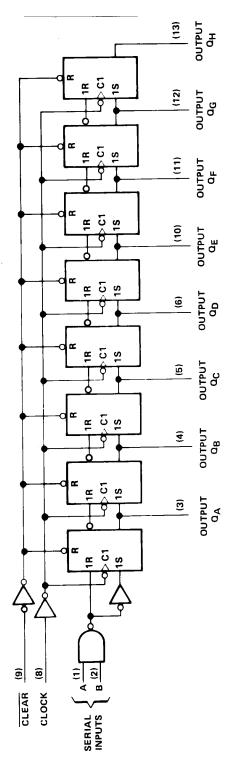


logic symbol†



 $^{^{\}dagger}$ This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

SN54164, SN74164 **8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS**

absolute maximum ratings over oprating free-air temperature range (unless otherwise noted)										
Input voltage										

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54164 SN74164			UNIT			
	MIN	NOM	MAX	MIN	NOM	MAX	O1411	
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V	
High-level output current, IOH			-400			-400	μΑ	
Low-level output current, IQL			8	<u> </u>		8	mA	
Clock frequency, fclock	0		25	0		25	MHz	
Width of clock or clear input pulse, tw	20			20			ns	
Data setup time, t _{su} (see Figure 1)	15			15			ns	
Data setup time, t _{SU} (Clear Inactive) (see Figure 1)	20			20			ns	
Data hold time, th (see Figure 1)	5			5	-		ns	
Operating free-air temperature, TA	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	•	SN54164			SN74164			UNIT
PARAMETER	TEST CONDITIONS	MIN	ТҮР‡	MAX	MIN	TYP‡	MAX	UNII
VIH High-level input voltage		2			2			٧
VIL Low-level input voltage				8.0			0.8	\ \
VIK Input clamp voltage	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	V
VOH High-level output voltage	$V_{CC} = MIN$, $V_{IH} = 2 V$, $V_{IL} = 0.8 V$, $I_{OH} = -400 \mu A$	2.4	3.2		2.4	3.2		٧
VOL Low-level output voltage	$V_{CC} = MIN, V_{IH} = 2 V,$ $V_{IL} = 0.8 V, I_{OL} = 8 mA$		0.2	0.4		0.2	0.4	V
I Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V,			1			1	mA
IIH High-level input current	V _{CC} = MAX, V ₁ = 2.4 V			40			40	μA
IL Low-level input current	V _{CC} = MAX, V _I = 0.4 V			-1.6			-1.6	mA
IOS Short-circuit output current §	V _{CC} = MAX	-10		-27.5	-9		-27.5	mA
	V _{CC} = MAX, V _{I(clock)} = 0.4 V	Î	30			30		mA
ICC Supply current	See Note 2 V _{I(clock)} = 2.4 V		37	54		37	54]

[†] For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC is measured with outputs open, serial inputs grounded, and a momentary ground, then 4.5 V, applied to clear.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$

	PARAMETER	TEST CONDIT	MIN	TYP	MAX	UNIT	
f _{max}	Maximum clock frequency		C _L = 15 pF	25	36		MHz
	Propagation delay time, high-to-low-level	1	C _L = 15 pF		24	36	ns
	Q outputs from clear input	n 800 o	C _L = 50 pF		28	42	
	Propagation delay time, low-to-high-level	R _L = 800 Ω,	C _{L.} = 15 pF	8	17	27	ns
+	Q outputs from clock input	See Figure 1	C _L = 50 pF	10	20	30] ""
	Propagation delay time, high-to-low-level		C _L = 15 pF	10	21	32	ns
tPHL			C _L = 50 pF	10	25	37]



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than two outputs should be shorted at a time.

SN54LS164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

absolute maximum ratings over operati	ting free-air temperature range (unless othe	rwise noted)
	SN54LS164	-55°C to 125°C
Storage temperature range	311/4L3104	
NOTE 1: Voltage values are with respect to network	k ground terminal.	

recommended operating conditions

		S	SN54LS164			SN74LS164			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2		_	V	
VIL	Low-level input voltage			0.7			0.8	V	
ЮН	High-level output current			- 0.4			- 0.4	mΑ	
lOL	Low-level output current			4			8	mA	
fclock	Clock frequency	0		25	0		25	MHz	
tw	Width of clock or clear input pulse	20			20			ns	
t _{su}	Data setup time (See Figure 1)	15			15			ns	
t _{su}	Clear inactive setup time (See Figure 1)	20			20		_	ns	
th	Data hold time (See Figure 1)	5			5			ns	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244552	TEST CONDITIONS!	S	N54LS1	64	S	UNIT			
PARAMETER	TEST CONDITIONS†	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNII	
VIK	$V_{CC} = MIN$, $I_I = -18 \text{ mA}$	·			- 1.5			- 1 .5	٧
V _{OH}	$V_{CC} = MIN$, $V_{IH} = 2 V$, V_{II} $I_{OH} = -0.4 \text{ mA}$	L = MAX,	2.5	3.5		2.7	3.5		٧
	$V_{CC} = MIN$, $V_{IH} = 2 V$,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
v_{OL}	V _{IL} = MAX	I _{OL} = 8 mA					0.35	0.5]
l _l	V _{CC} = MAX, V _I = 7 V			·	0.1			0.1	mA
ін	$V_{CC} = MAX$, $V_I = 2.7 V$			20			20		μΑ
ΙΙL	$V_{CC} = MAX$, $V_I = 0.4 V$				-0.4			-0.4	mA
los	V _{CC} = MAX		- 20		- 100	- 20		- 100	mA
lcc	V _{CC} = MAX, See Note 3	_		16	27		16	27	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		25	36		MHz
tPHL	Propagation delay time, high-to-low-level Q outputs from clear input	$R_L = 2 k\Omega$, $C_L = 15 pF$,		24	36	ns
tPLH	Propagation delay time, low-to-high-level Q outputs from clock input	See Figure 1		17	27	ns
tPHL	Propagation delay time, high-to-low-level Q outputs from clock input			21	32	ns



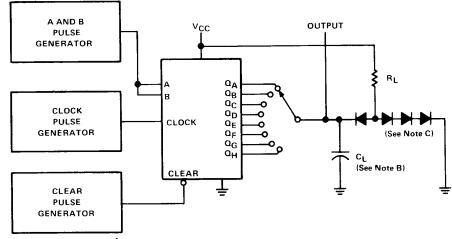
 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

⁵Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

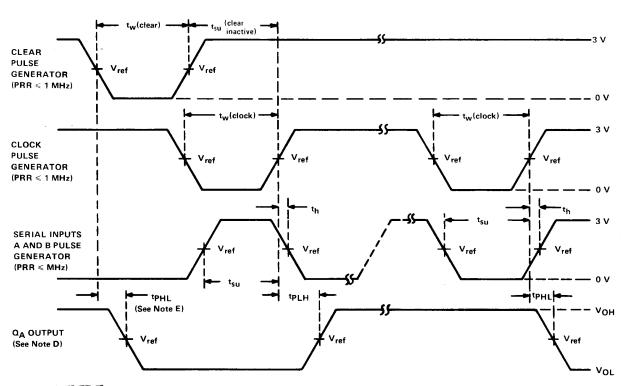
NOTE 3: I_{CC} is measured with outputs open, serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then 4.5 V applied to clear.

SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

- NOTES: A. The pulse generators have the following characteristics: duty cycle \leq 50%, $Z_{out} \approx$ 50 Ω ; for '164, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns, and for LS164, $t_r \leq$ 15 ns, $t_f \leq$ 6 ns.
 - B. C_L includes probe and jig capacitance.
 - C. All diodes are 1N3064 or equivalent.
 - D. QA output is illustrated. Relationship of serial input A and B data to other Q outputs is illustrated in the typical shift sequence.
 - E. Outputs are set to the high level prior to the measurement of tpHL from the clear input.
 - F. For '164, $V_{ref} = 1.5 \text{ V}$; for 'LS164, $V_{ref} = 1.3 \text{ V}$.

FIGURE 1-SWITCHING TIMES







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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Samples
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
JM38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
JM38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
JM38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
JM38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
JM38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
JM38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
M38510/30605B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Samples
M38510/30605B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Samples
M38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
M38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
M38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
M38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
M38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
M38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
M38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
SN54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS164J	Samples
SN54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS164J	Samples
SN74LS164DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70 LS164		Samples
SN74LS164N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SN74LS164NSR	ACTIVE	so	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 164FK	Samples
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 164FK	Samples
SNJ54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164J	Samples
SNJ54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164J	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS164W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164W	Samples
SNJ54LS164W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54LS164, SN54LS164-SP, SN74LS164:

● Catalog : SN74LS164, SN54LS164

• Military : SN54LS164

• Space : SN54LS164-SP

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

• Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS164NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN74LS164DR	SOIC	D	14	2500	356.0	356.0	35.0	
SN74LS164NSR	SO	NS	14	2000	356.0	356.0	35.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/30605B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/30605BDA	W	CFP	14	1	506.98	26.16	6220	NA
JM38510/30605SDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/30605B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/30605BDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/30605SDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS164FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS164W	W	CFP	14	1	506.98	26.16	6220	NA

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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